



**THE DATASHEET OF
SF2161E**



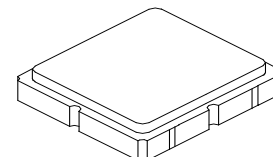
- **Low Insertion Loss SAW RF Filter**
- **3.0 x 3.0 x 1.3 mm Surface-Mount Case**
- **No Matching Circuit Required**
- **Complies with Directive 2002/95/EC (RoHS)**
- **Moisture Sensitivity Level: 1**

Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	+10	dBm
DC Voltage on any Non-ground Terminal	3	Volts
Operating Temperature Range	-20 to +70	°C
Storage Temperature Range in Tape and Reel	-30 to +85	°C
Maximum Soldering Profile, 5 Cycles/10 seconds Maximum	265	°C

SF2161E

**2650 MHz
SAW Filter**



SM3030-6

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_c	1		2650		MHz
Insertion Loss	IL			2.0	3.5	MHz
Amplitude Ripple, 2615 to 2685 MHz				0.9	2.5	dB _{P-P}
Attenuation Referenced to 0 dB:						
DC to 2300 MHz			23.0	27.5		dB
2300 to 2500 MHz			25.0	32.0		
2800 to 4000 MHz			30.0	34.0		
4000 to 5000 MHz			20.0	32		
VSWR, 2615 to 2685 MHz				1.6:1	2.3:1	
Source Impedance	Z_S			50		Ω
Load Impedance	Z_L			50		Ω

Single-Ended Input / Output Impedance Match	No matching network required for operation at 50 ohms
Case Style	SM3030-6 3 x 3 mm Nominal Footprint
Lid Symbolization, Y=year, WW=week, S=shift	848 YWWS

Electrical Connections

Connection	Terminals
Input	2
Output	5
Ground	All others

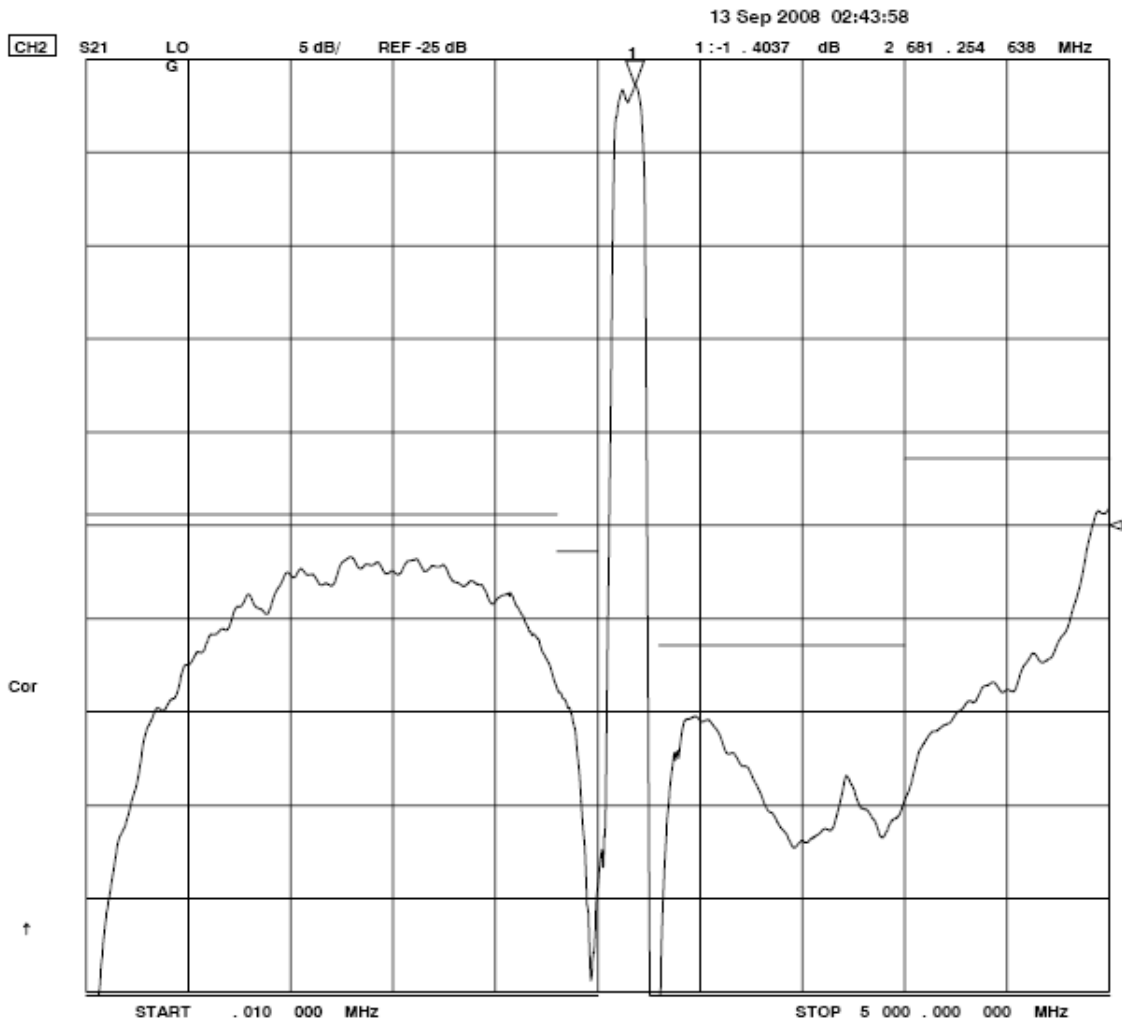


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

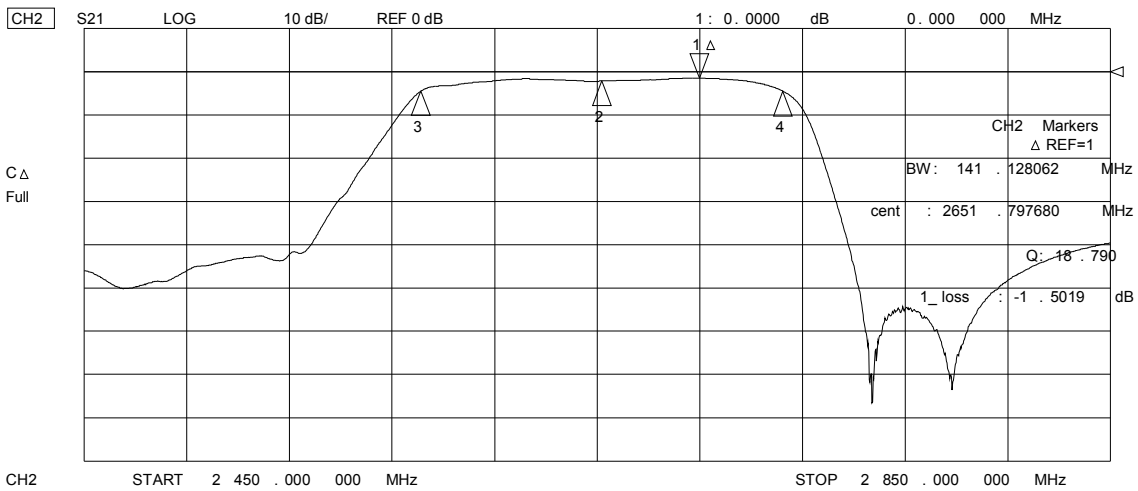
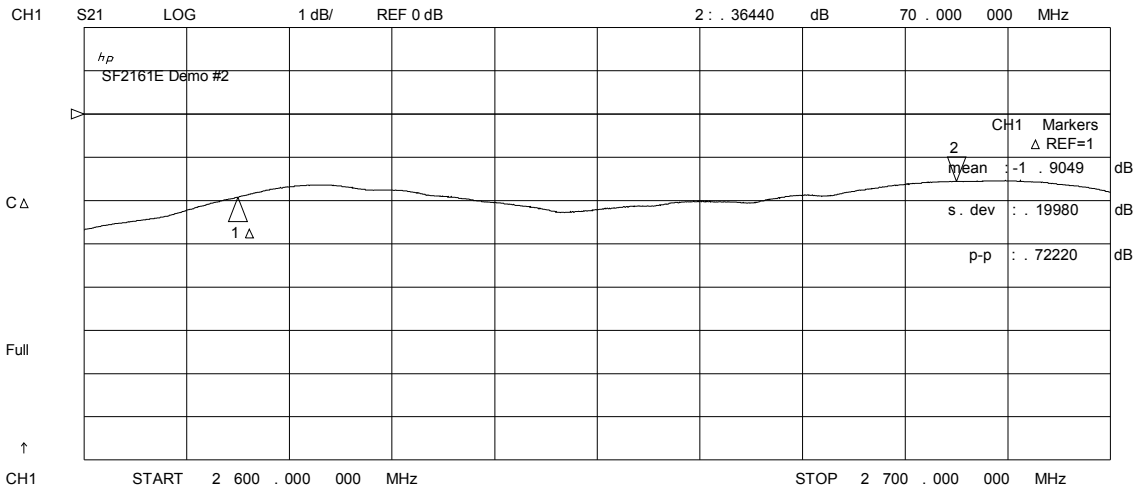
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

Broadband Filter Response



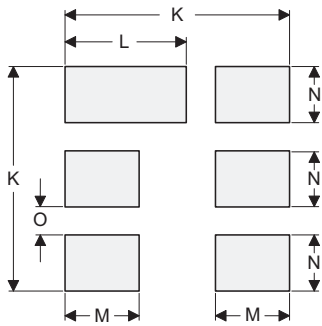
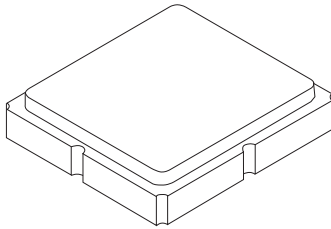
Passband Filter Response

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SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

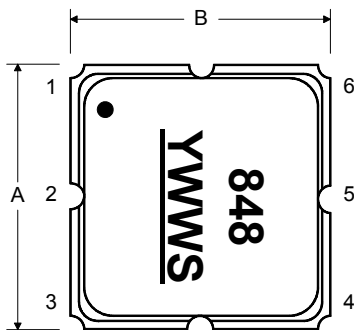
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

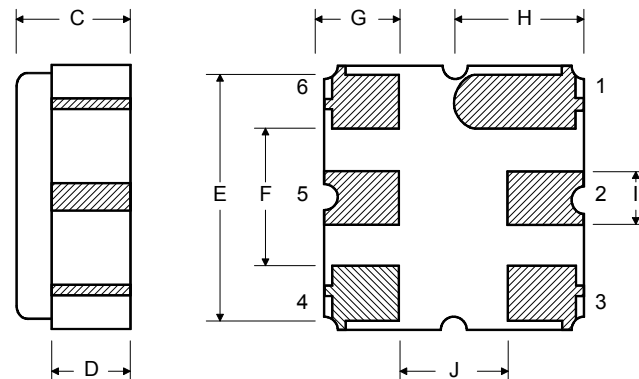
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic

Top View

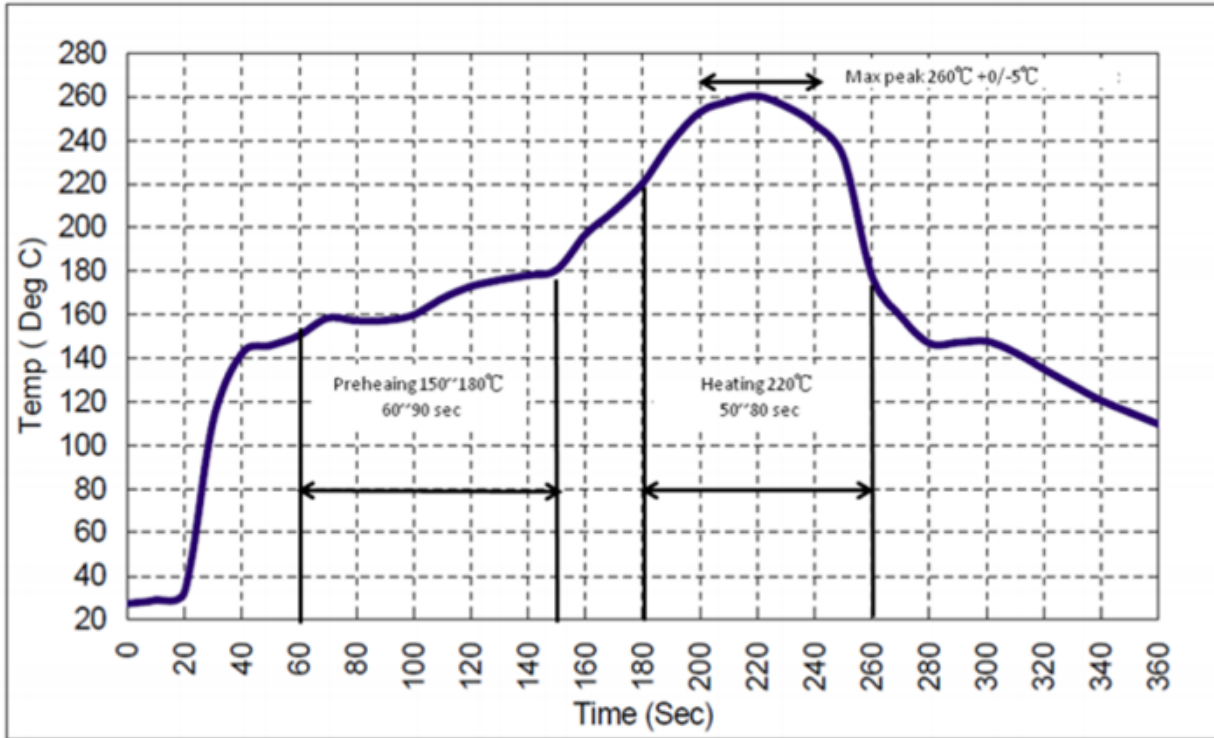


Bottom View



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180° for 60~90 seconds.
2. Ascending time to preheating temperature 150° shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C peak (10 seconds.)
4. Time: 5 times maximum



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